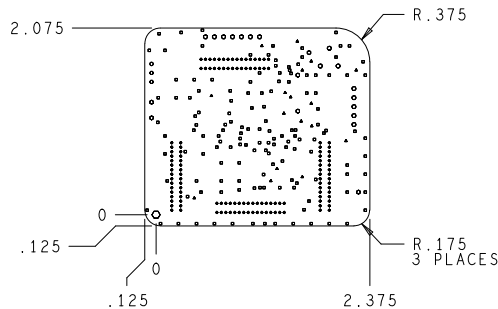



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
01	ALPHA RELEASE	05/27/12	RKAD
02	ALPHA RELEASE	08/31/12	RKAD
03	ADDED LCD INCREASE BOARD SIZE	09/30/12	RKAD
04	REMOVED P3_6 & P3_7 NETS FROM J3.	12/04/12	RKAD
05	ROTATED P1. CHANGED BOARDOUTLINE.	01/08/13	RKAD
06	NET CHANGED P3_0,P3_2,P3_6,P3_7. ADDED C12, R14. ADDED SILK.	01/29/13	RKAD

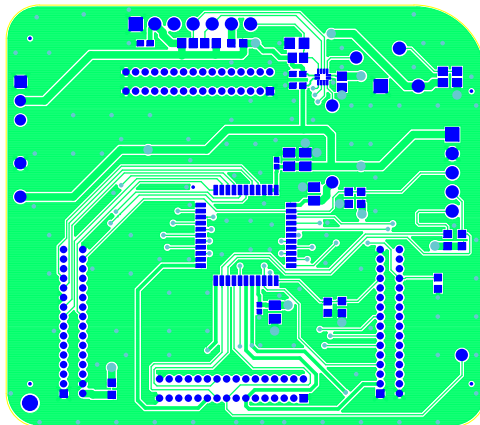


DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	10.0	+3.0/-10.0	PLATED	141
•	28.0	+3.0/-3.0	PLATED	128
•	30.0	+3.0/-3.0	PLATED	17
•	40.0	+3.0/-3.0	PLATED	1
•	40.0	+3.0/-3.0	PLATED	15
•	40.0	+3.0/-3.0	PLATED	2
•	43.0	+3.0/-3.0	PLATED	6
•	90.0	+3.0/-3.0	NON-PLATED	1

NOTES:(UNLESS OTHERWISE SPECIFIED)

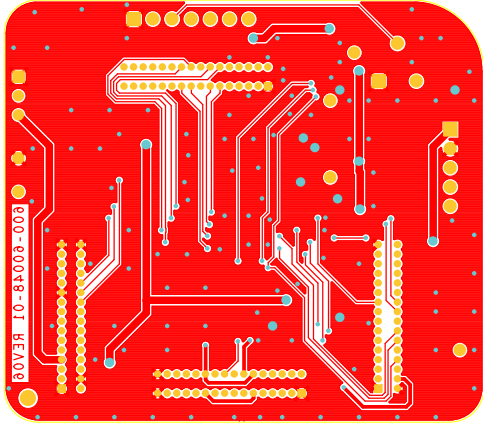
1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
 - A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
 - B. USE HTE COPPER 1 oz. EXTERNAL LAYERS AND 1 oz. COPPER FOIL FOR INTERNAL LAYER 2. USE 3 oz. COPPER FOR INTERNAL LAYER 3.
 - C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
3. DRILLING:
 - A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/- .003 TOL. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
 - B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
 - A. COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
 - A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
 - B. FABRICATOR TO ETCH DATE CODE AND LOGO ON SECONDARY SIDE.
6. FINAL FABRICATION:
 - A. SOLDERMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **RED**
7. FINISH:
 - A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
 - B. NICKEL THICKNESS: 100-200 MICROINCHES.
 - C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0), DATE CODE (WYYY), AND RoHS COMPLIANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .010 in/in.

UNLESS OTHERWISE SPECIFIED		SIGNATURES		DATE	 CYPRESS SEMICONDUCTOR 2700 162nd St. SW. BLDG D Lynnwood, WA 98087 (425)-787-4466
DIMENSIONS ARE IN INCHES		DRAWN	ZMK	01/28/13	
TOLERANCES ON: ANGLES +/- 2°		CHECKED	RKAD	01/29/13	
2 PL DECIMALS +/- .010		ENGRG	RKAD	01/29/13	
3 PL DECIMALS +/- .005		ISSUED			
THIRD ANGLE PROJECTIONS					
CYPRESS PROPRIETARY					
THIS DOCUMENT CONTAINS CONFIDENTIAL					
PROPRIETARY INFORMATION THAT IS					
CYPRESS SEMICONDUCTOR PROPERTY.					
DO NOT DISCLOSE TO OR DUPLICATE FOR					
OTHERS EXCEPT AS AUTHORIZED BY CYPRESS.					
SIZE	FSCM NO	DWG NO	REV		
C		610-60046-01	06		
SCALE: 1/1		SHEET: 1 OF 1			



600-60048-01 REV06 PRIMARY SIDE

000-00048-01 REV00 SECONDARY SIDE





000-00048-01 REV00 SECONDARY SILKSCREEN

